

IEEE EPS Technical Webinar with University Malaya

3rd May 2024



The graphic features a light blue background with a circuit board pattern. On the left is the IEEE EPS logo. The main text is centered and reads 'EPS Webinar Series 2024' followed by the topic 'Advancements in Lead-Free Solder Electrodeposition and Joint Behaviour for Electronic Packaging Applications'. A photo of Dr. Goh Yingxin is shown on the left, with her name and title below it. To the right of the photo is a paragraph of text describing the webinar's content. In the center, there is a box with registration details: date (3 MAY 2024), time (10 - 11AM), platform (IEEE CISCO WebEx), and a 'REGISTER NOW!' button with a QR code and 'SCAN ME' text below it. The IEEE logo is in the top right corner, and the website 'www.ieee.org' is at the bottom right.

IEEE ELECTRONICS PACKAGING SOCIETY

EPS Webinar Series 2024

Advancements in Lead-Free Solder Electrodeposition and Joint Behaviour for Electronic Packaging Applications



Dr Goh Yingxin
Senior Lecturer
Department of Mechanical Engineering
Universiti Malaya

This webinar offers an exploration into the technical challenges and advancements in electrodeposition of lead-free solder alloys. The scientific principles governing the successful electrodeposition of these alloys will be discussed, as well as the use of advanced strategies and additives for alloy composition and quality control. Additionally, the mechanisms of deformation and fracture in electroplated solder joints will be presented, focusing on how factors such as reflow temperature influence their strength and reliability. Last but not least, the potential implications of these advancements for the electronics industry will be uncovered.

Date: 3 MAY 2024 (FRI)
Time: 10 - 11AM (Malaysia, GMT +8:00)
Platform: IEEE CISCO WebEx

REGISTER NOW!
(Click the link/scan the QR for registration)
*E certificates will be provided to all participant



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- IEEE EPS Malaysia has successfully organized a Technical Webinar with Dr Goh Ying Xin from University Malaya, on the topic of Advancements in Lead-Free Solder Electrodeposition and Joint Behavior for Electronic Packaging Applications.
- Dr Goh expounded on the advancements of lead-free solder alloys and associated technical challenges, and a good sharing on the scientific principles governing the successful electrodeposition of these alloys.
- > 40 participants joined the webinar with strong engagement from the audience.